

IN THE CLAIMS:

Claims 1, 23 and 25 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Twice Amended) A method of forming an integrated circuit package, the method comprising:
forming a lead frame having a plurality of conductors and at least one alignment feature electrically isolated from the plurality of conductors;
coupling at least some of the plurality of conductors to a semiconductor die;
encapsulating the semiconductor die and a portion of the lead frame with an insulating material;
and
removing the at least one alignment feature subsequent the encapsulating the semiconductor die and a portion of the lead frame.
2. (cancelled)
3. (previously amended) A method of forming an integrated circuit package, the method comprising:
providing a plurality of conductors and at least one alignment feature;
coupling at least some of the plurality of conductors to a semiconductor die; and
encompassing the semiconductor die, a portion of each of the plurality of conductors, and
substantially encompassing the at least one alignment feature with an insulating material.

4. (previously twice amended) A method of forming and testing an integrated circuit package, the method comprising:
providing a plurality of conductors and at least one alignment feature;
electrically coupling at least some of the plurality of conductors to a semiconductor die;
encompassing the semiconductor die, a portion of each of the plurality of conductors, and
substantially encompassing the at least one alignment feature with an insulating material;
coupling the at least one alignment feature encompassed by the insulating material with a portion
of a testing device; and
testing the integrated circuit package through at least some of the electrically coupled conductors.

5-17. (cancelled)

18. (original) The method according to claim 1, further comprising forming the at least one alignment feature to include at least one aperture.

19. (original) The method according to claim 1, further comprising forming the at least one alignment feature to include a plurality of apertures.

20. (original) The method according to claim 1, further comprising forming a separation line in the lead frame and wherein removing the at least one alignment feature further comprises removing the at least one alignment feature along the separation line.

21. (original) The method according to claim 20, wherein the forming a separation line in the lead frame includes perforating the separation line.

22. (original) The method according to claim 1, further comprising forming the at least one alignment feature to include a tab.

23. (Amended) A method of forming and testing an integrated circuit package, the method comprising:
forming a lead frame having a plurality of conductors and at least one alignment feature electrically isolated from the plurality of conductors;
coupling at least some of the plurality of conductors to a semiconductor die;
encapsulating the semiconductor die and a portion of the lead frame with an insulating material;
coupling the at least one alignment feature with a portion of a testing device;
testing the integrated circuit package through at least some of the electrically coupled conductors;
decoupling the at least one alignment feature from the portion of the testing device; and
removing the at least one alignment feature subsequent the decoupling the at least one alignment feature from the portion of the testing device.

24. (original) The method according to claim 3, further comprising forming the at least one alignment feature to include an alignment cut-out.

25. (Amended) The method according to claim 3, further comprising ~~providing coupling~~ a heat spreader to an external surface of the insulating material, ~~and~~ forming the at least one other alignment feature in the heat spreader.

26. (original) The method according to claim 3, further comprising providing a tie bar and forming the at least one alignment feature in the tie bar.

IN THE DRAWINGS:

Applicants submit herewith, under cover of a separate Letter to the Official Draftsperson, proposed corrections to FIG. 2 of the drawings. Specifically, the lead line associated with reference numeral 200 has been changed to more generally indicate the lead frame with which it is associated. The proposed correction has been marked in red.

Applicants further submit new FIG. 9 which includes a flow chart indicating a method of forming and testing an integrated circuit device. The subject matter of FIG. 9 is set forth in the as-filed specification including, for example, at page 4, lines 18-25, and page 10, line 20 through page 11, line 16. Applicants submit that no new subject matter has been added by the introduction of FIG. 9.

Applicants respectfully request approval of corrected FIG. 2 and new FIG. 9.

Applicants also submit herewith corrected formal drawings, under cover of a separate Transmittal of Formal Drawings. Applicants respectfully request approval of the corrected formal drawings.